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## Claims:

1. Method for mounting a switching module, in which a circuit support (1, 42) is inserted into the basic housing element (10, 35, 44) with its flat sides (63, 64) facing walls (20, 21, 46, 53) of a basic housing element (10, 35, 44) and the basic housing element (10, 35, 44) is closed with the aid of cover elements (6, 25, 37, 47, 52), characterized in that a longitudinally extended pressure strip (26, 49) is inserted between the circuit support (1, 42) and the basic housing element (10, 35, 44), by means of which a compression force acting on a flat side (64) of the circuit support (1, 42) is applied and that the pressure strip (26, 49) is guided by guide means (17, 18, 19, 50) configured on the inside of the basic housing element (10, 44).
2. Method according to Claim 1, characterized in that the pressure strip (26, 49) configured as a tension spring is charged during insertion of the circuit support (1, 42) and released to fix the circuit support (1, 42) in the basic housing element (10, 44).
3. Method according to Claim 1, characterized in that the pressure strip (26, 49) configured as a compression spring for fixing the printed circuit board (1, 42) is subject to a pressure (57) that compresses the compression spring.
4. Method according to Claim 3, characterized in that the pressure (57) is applied by the cover elements (47, 52) of the basic housing element (44)

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5. Method according to one of Claims 1 to 4,  
characterized in that the pressure strip (26, 49) is guided  
inside the basic housing element (10, 44) by an encapsulated  
5 guide groove (17, 50).

6. Method according to one of Claims 1 to 5,  
characterized in that the circuit support (1, 42) is guided by  
guide elements (16, 18, 19, 36, 45) during insertion into the  
10 basic housing element (10, 35, 44).

7. Method according to Claim 6,  
characterized in that the circuit support (1, 42) is fitted  
with components on both sides before insertion into the basic  
15 housing element (10, 35, 44).

8. Method according to one of Claims 1 to 7,  
characterized in that a cover element (6, 47) is fixed to the  
circuit support (1, 42) before insertion of the circuit  
20 support (1, 42) into the basic housing element (10, 35, 44).

9. Method according to Claim 8,  
characterized in that contact means (5, 7, 48) configured on  
the cover element (6, 47) are connected to the circuit support  
25 (1, 42) before insertion of the circuit support (1, 42) into  
the basic housing element (10, 35, 44).

10. Method according to one of Claims 1 to 9,  
characterized in that the pressure strip (26, 49) is inserted  
30 into the basic housing element (10, 35, 44) together with the  
circuit support (1, 42)).

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11. Method according to one of Claims 1 to 10,  
characterized in that a cover element (25, 47) provided with  
the pressure strip (26, 49) is attached to an opening (15, 43)  
5 in the basic housing element (10, 35, 44).
12. Method according to one of Claims 1 to 11,  
characterized in that the pressure strip (26) is tailored to  
the length of the basic housing element (10) at breaking  
10 points (34) before insertion into the basic housing element  
(10).
13. Method according to one of Claims 1 to 12,  
characterized in that the pressure strip (26) is held  
15 positively in a recess (33) in an opposite cover element (6).
14. Method according to one of Claims 1 to 13,  
characterized in that a saw-tooth profile (32) is configured  
on the pressure strip (26) and is held positively in latch  
20 points on the recess (33).
15. Method according to Claim 13 or 14,  
characterized in that the basic housing element (10, 35) is  
clamped between opposite cover elements (6, 25, 37).
- 25 16. Method according to one of Claims 1 to 15,  
characterized in that a cover element (37) is fixed to the  
circuit support (1) by way of clamping means (39, 40) during  
attachment of a cover element (37) to an opening (15) in the

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basic housing element (35).

17. Method according to one of Claims 1 to 16,  
characterized in that the openings (12, 15) on the transverse  
5 sides (11, 14) of the basic housing element (10, 35) are sealed  
by means of identical seals (24, 30).

18. Switching module with an electronic component arranged  
inside a housing,  
10 characterized in that the switching module can be produced  
using a method according to at least one of Claims 1 to 17.

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